1

OMRON **B3B Tactile Switch (Ultra-low Profile)**

Ultra-low Profile Tactile Switch with a Thickness of Only 0.47 mm

- Surface-mounting model with dimensions of 4.7 x 4.7 x 0.47 mm allows high-density mounting.
- Contributes to making devices with this Tactile Switch more compact, slim, and lightweight.
- Available on embossed tape that enables automatic mounting.
- Dust-sealed construction provides high reliability.
- Available for reflow soldering.

Ordering Information

Model Number Legend **B3B-1002P**

- 12 34
- 1. Size

1: 4.7 mm x 4.7 mm

List of Models

Item	Model
Embossed tape packing (unit: 6,000 pcs.)	B3B-1002P

Note: The Switches are available in units of 6,000 pieces. Orders must be made in units of 6,000 pieces; no partial units can be shipped.

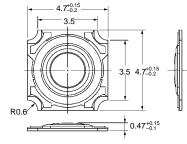
Specifications

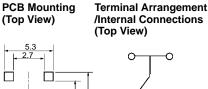
Ratings/Characteristics

Switching capacity	1 to 20 mA, 5 to 15 VDC, (resistive load)	
Contact configuration	SPST-NO	
Contact material	Silver plating	
Contact resistance	1 Ω max. (initial value) (rated: 1 mA, 5 VDC)	
Insulation resistance	100 MΩ min. (at 100 VDC)	
Dielectric strength	250 VAC, 50/60 Hz for 1 min	
Bounce time	10 ms max.	
Vibration resistance	Malfunction: 10 to 55 Hz, 1.5-mm double amplitude	
Shock resistance	Destruction: 735 m/s ² min. {approx. 75G min.}	
Life expectancy	50,000 operations min.	
Ambient temperature	Operating: -25°C to 70°C (with no icing)	
Ambient humidity	Operating: 25% to 85%	
Weight	Approx. 0.01 g max.	

Dimensions

Note: All units are in millimeters unless otherwise indicated.





2.7 5.3

	ltem	Standard value	
ſ	Operating force (OF)	1.58±0.49 N {160±50 gf}	
	Releasing force (RF)	0.29 N {30 gf} min.	
	Pretravel (PT)	0.2±0.1 mm	

Operating Characteristics

Insulating Tape

- **Operating Force (OF)** 1.58 N 2:
 - **Shipment Package**
 - P: Embossed tape
- 2. 0: None
- 3.





B3B

Washing

No washing is allowed after soldering to prevent detergent or flux

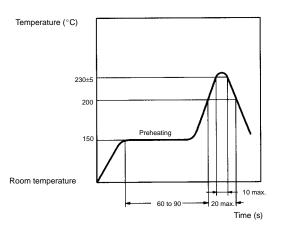
from entering into the Switch. Doing so may cause malfunction.

Precautions

Soldering

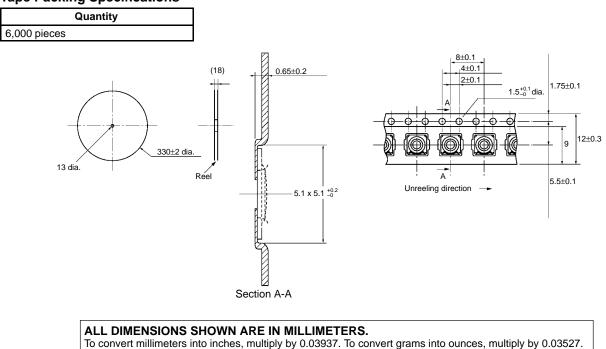
Soldering Conditions for Reflow Soldering

Carry out soldering within the temperature curve shown in the following illustration.



Note: The above curve is given on condition that the thickness of the PCB is 1.6 mm.

Since the peak value may vary depending on the reflow soldering device, be sure to conduct a verification test in advance.



Tape Packing Specifications

Cat. No. A110-E1-4 In the interest of product improvement, specifications are subject to change without notice.

OMRON Corporation

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